

CLAIMS

1. An electrically conductive paste which is used for forming wiring conductors and which is co-fired in firing for sintering ceramic layers in a multilayer ceramic substrate provided with the plurality of ceramic layers laminated and the wiring conductors disposed in association with the ceramic layers, the electrically conductive paste comprising

a metal powder, a glass frit, and an organic vehicle, wherein an inorganic component, which is not sintered at a sintering temperature capable of sintering the ceramic layer in the firing, is disposed on particle surfaces of the metal powder, and

the glass frit has a softening point 150°C to 300°C lower than the sintering temperature.

2. The electrically conductive paste according to Claim 1, wherein the sintering temperature is 800°C to 1,000°C, and the softening point of the glass frit is 650°C to 850°C.

3. The electrically conductive paste according to Claim 1, wherein a temperature at which $\log(\eta/\text{Pa}\cdot\text{s}) = 4$ holds for the viscosity of the glass frit is present within the range of 800°C to 950°C.

4. The electrically conductive paste according to Claim 1, wherein the content of the inorganic component is 0.5 to 8 percent by weight relative to the total weight of the metal

powder and the inorganic component.

5. A multilayer ceramic substrate comprising a plurality of ceramic layers laminated and wiring conductors disposed in association with the ceramic layers, wherein the wiring conductors are composed of sintered bodies of the electrically conductive paste according to any one of Claims 1 to 4.

6. The multilayer ceramic substrate according to Claim 5, wherein the wiring conductors include via hole conductors disposed penetrating specific layers of the ceramic layers.